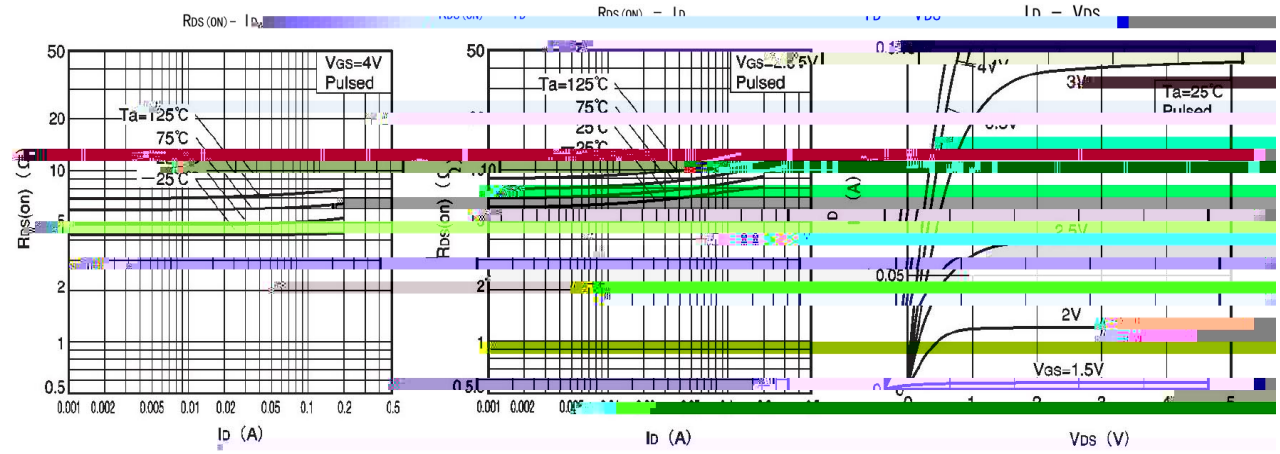
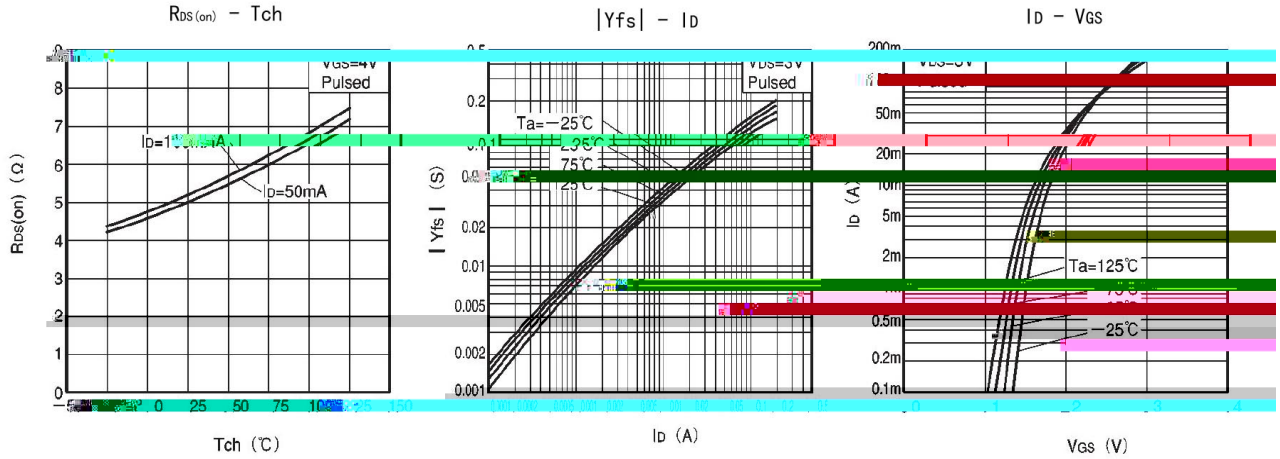
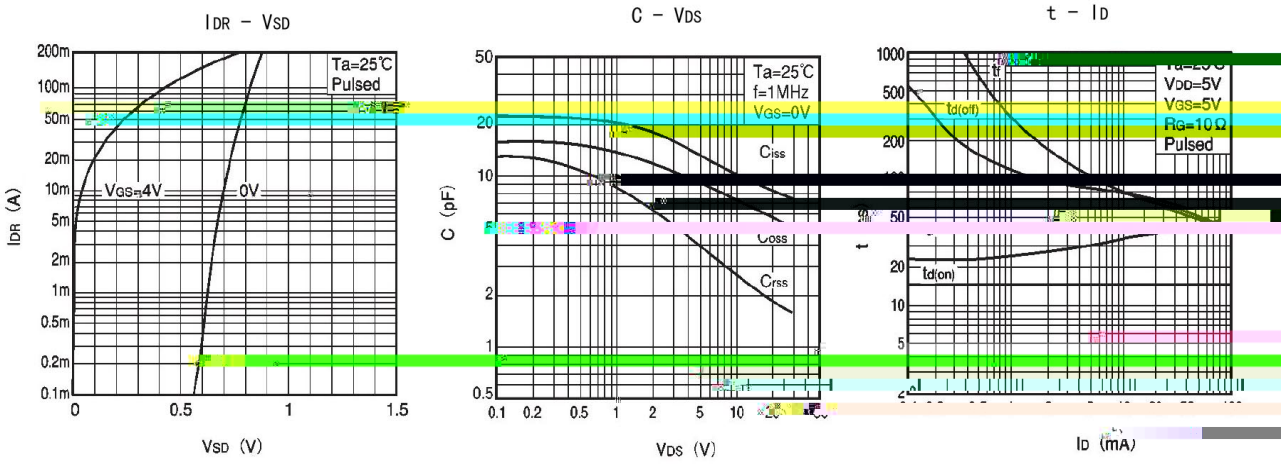
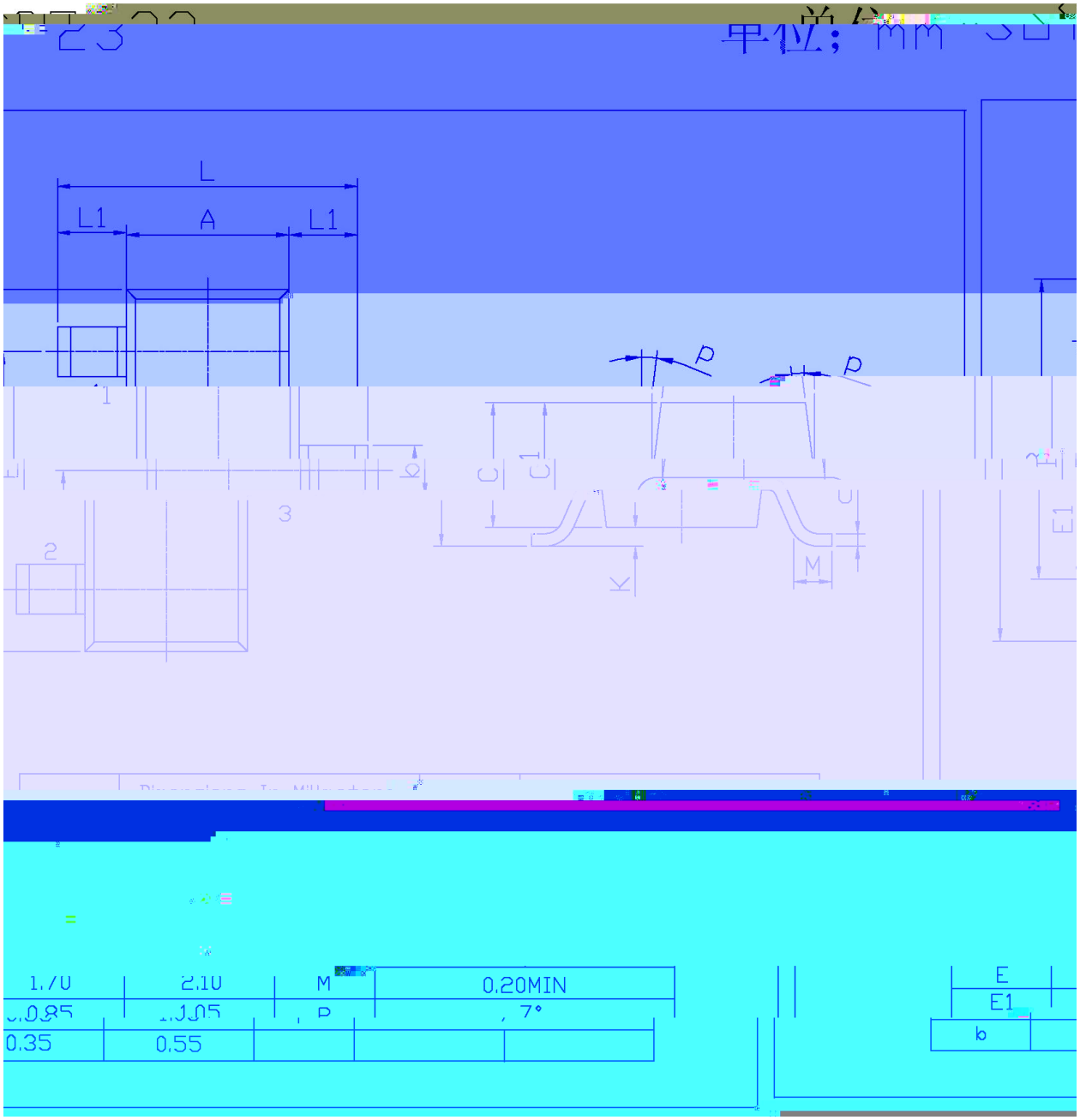
## / Electrical Characteristic Curve



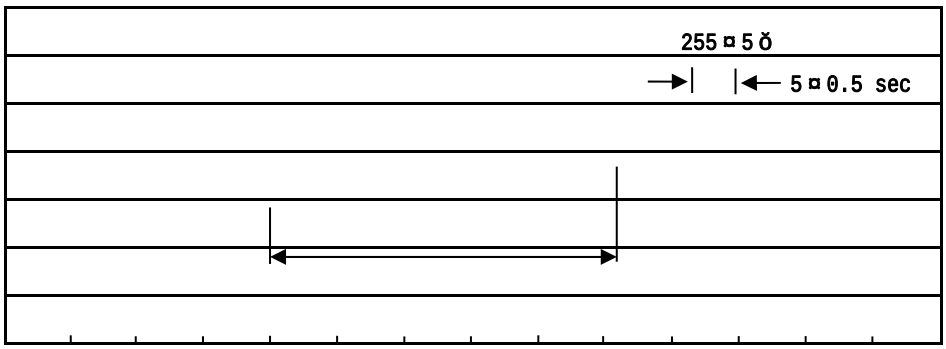



## / Package Dimensions



## ( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)




ب χ

| | | | | | | | |
|---|---|---|---|---|---|---|---|
| 1 | أ | 150 | 200 | | ژ 60 | 120sec; | 1.Preheating:150~200 , Time:60~120sec. |
| 2 | | 255±5 | | ژ | ۸ | 5±0.5sec; | 2.Peak Temp.:255±5 , Duration:5±0.5sec. |
| 3 | | ۱ | ھ | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

Note:

## / Resistance to Soldering Heat Test Conditions

χ 260±5 ژ χ 10±1 sec. Temp.:260±5 Time:10±1 sec

## / Packaging SPEC.

` Ь / REEL

| Package Type | Units | | | | | Dimension | | (unit mm³) |
|---|---|---|---|---|---|---|---|---|
| | | | | | | | | |
| | | | | | | | | |

## / Notices